Gillientec

Use GILLION, Become Giant

Thermal Release Tape

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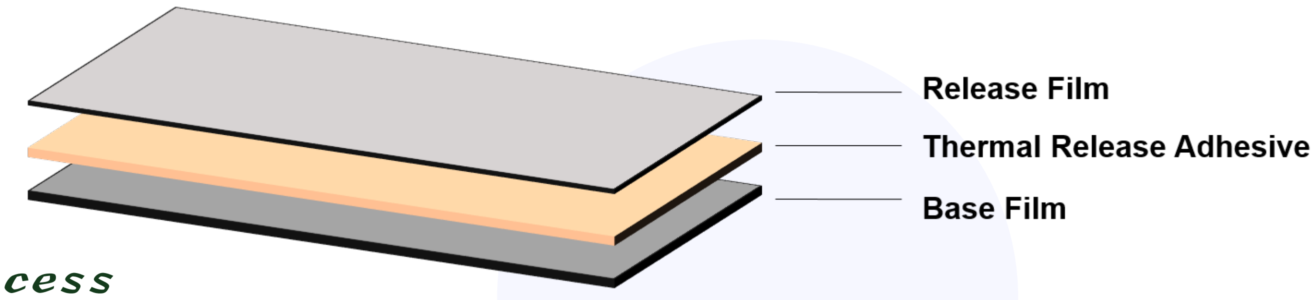
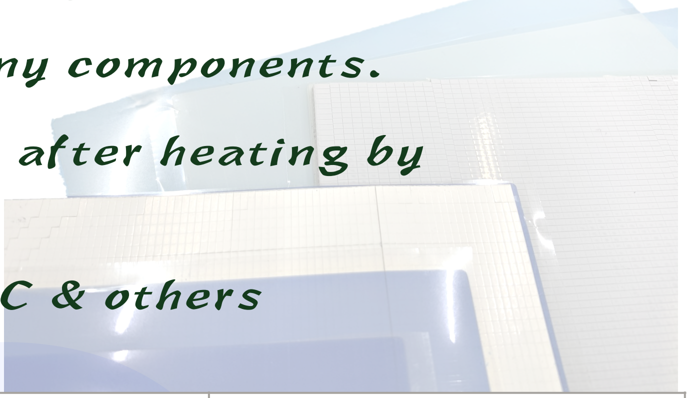
Application

- MLCC cutting process
- LED chip grinding process
- Glass cutting process
- Chip/Component dicing process
- Use for temporary fixed purpose



Feature

- Make for semiconductor device 、electronic component 、optoelectronics 、LED 、MLCC component cutting or grinding process.
- Qualities have been certificated by international leading companies.
- Excellent adhesion, no position shift when cutting tiny components.
- Electronic components are easily released from tape after heating by hot plate or oven.
- It shows excellent performance and stability in MLCC & others electronic component manufacturing industry.



Model	Base film material / thickness (um)	Adhesive thickness (um)	Adhesion (N/25mm)	Color	Thermal release temperature (°C)	Process
GTR 501A2	PET / 50	35	4	Milky white	105	Protecting process
GTR 52AA2	PET / 100	50	15		105	MLCC component cutting
GTR 515A2		40	4		120	For passive component SAT operating tape
GTR 561A2		50	15		130	MLCC component cutting

Your desire, we design

Customize your material